



Special Issue on Ceramic Materials

Call for Papers

A ceramic is a material that is neither metallic nor organic. It may be crystalline, glassy or both crystalline and glassy. Ceramics are typically hard and chemically non-reactive and can be formed or densified with heat. Ceramics are more than pottery and dishes: clay, bricks, tiles, glass, and cement are probably the best-known examples. Ceramic materials are used in electronics because, depending on their composition, they may be semiconducting, superconducting, ferroelectric, or an insulator. Ceramics are also used to make objects as diverse as spark plugs, fiber optics, artificial joints, space shuttle tiles, cooktops, race car brakes, micropositioners, chemical sensors, self lubricating bearings, body armor, and skis. The goal of this special issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in the area of **ceramic materials**.

In this special issue, we intend to invite front-line researchers and authors to submit original research and review articles on exploring **ceramic materials**. Potential topics include, but are not limited to:

- Crystalline ceramics
- Noncrystalline ceramics
- Mechanical properties of ceramics
- Thermal properties of ceramics
- Electrical properties of ceramics
- Optical properties of ceramics
- Rare earth industry and environmental protection
- Applications of ceramics materials

Authors should read over the journal's [For Authors](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).

Please kindly specify the “**Special Issue**” under your manuscript title. The research field “**Special Issue - Ceramic Materials**” should be selected during your submission.

Special Issue Timetable:

Submission Deadline	March 30th, 2021
Publication Date	May 2021



Guest Editor:

For further questions or inquiries,
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